

L Number	Hits	Search Text	DB	Time stamp
-	0	soi and ((via hole open\$3 contact) with fox) and (thin\$4 with backside with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 15:12
-	124	soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 11:38
-	75	(soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:41
-	69	soi and (via hole open\$3 contact) and (backside with etch\$3) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 14:54
-	41	(soi and (via hole open\$3 contact) and (backside with etch\$3) and (backside with (connection or contact))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:00
-	36	(form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:09
-	25	((form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3)) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:23
-	2	5426072.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/24 15:23
-	106	soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:10
-	45	(soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/04/25 15:04
-	2559	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 15:12
-	404	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:19
-	124	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:22
-	26	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:20
-	69	((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
-	0	((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35

	13	((vertical\$2 or vertigal) adj integration) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
	136	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
	0	((vertical\$2 or vertigal) adj integratable) and 438/\$3.ccls. and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:34
	3	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((back or rear) adj side)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:35
	0	((((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((back or rear) adj side)) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:36
	25	((vertical\$2 or vertigal) adj integrat\$4) and 438/\$3.ccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/08 18:36
	3347	(438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:41
	2559	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:42
	42	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 14:42
	24	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic))) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15
	134	soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:06
	3	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and (soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:09
	39	(form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:09
	2	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and (form\$3 with (via hole open\$3 contact) with (field adj oxide)) and (backside with etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:10
	113	soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:10
	10	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and (soi and (vertical with interconnect) and field and (substrate with (etch\$3 or remov\$3))))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15

-	73	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((thin\$3 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15
-	28	((438/618 or 438/620 or 438/637 or 438/667 or 438/672 or 438/675).ccls.) and ((thin\$3 or remov\$3) with substrate) and soi) and @ad<19990423	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/10/09 15:15
-	2	5426072.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 12:16
-	91	5426072.URPN.	USPAT	2004/04/01 15:32
-	7	("3602981" "3623219" "4022927" "4423435" "4980308" "5244817" "5279991").PN.	USPAT	2004/04/01 16:19
-	130	((((three adj dimensional) or "three-dimensional" or "3d") with ((integrated adj circuit) or ic)) and 438/\$3.cccls. and @ad<19990423) and ((thin\$4 or remov\$3) with substrate) and soi	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:33
-	22	((three adj dimensional) or "three-dimensional" or "3d") same (soi or (silicon adj3 insulat\$3)) same (interconnect or vertical) and (@ad<19990423 or @rlad<19990423)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:46
-	2423	((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:47
-	12	((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)) and interconnect and 438/459.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/04/01 16:50
-	260	((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)) and interconnect and 438/\$3.cccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 15:13
-	169	soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 11:40
-	102	(soi and (via hole open\$3 contact) and (thin\$4 with substrate) and (backside with (connection or contact))) and (@ad<19990423 or @rlad<19990423)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 11:40
-	2	5426072.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 12:16
-	102	5426072.URPN.	USPAT	2004/08/25 12:16
-	12	("4889832" "5225771" "5424245" "5426072" "5563084" "5627106" "5767001" "5814889" "5825080" "5851894" "5877034" "6242778").PN.	USPAT	2004/08/25 12:28
-	102	5426072.URPN.	USPAT	2004/08/25 12:32
-	3	("5426072" "5587341" "6080264").PN.	USPAT	2004/08/25 14:46
-	8	("4468857" "5087585" "5289031" "5426072" "5517047" "5696386" "5770487" "5786638").PN.	USPAT	2004/08/25 14:51
-	1	5780354.URPN.	USPAT	2004/08/25 15:07

-	137594	(annular or ring) with metal	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 15:12
-	2918	((three adj dimensional) or "three-dimensional") with ((integrated adj circuit) or ic)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 15:12
-	2463	((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)) ((annular or ring) with metal) and (((three adj dimensional) or "three-dimensional" or "3d") and (soi or (silicon adj3 insulat\$3)) and ((thin\$4 or etch\$3 or remov\$3) with substrate) and (@ad<19990423 or @rlad<19990423)))	USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 15:14
-	63		USPAT; US-PGPUB; EPO; JPO; DERWENT	2004/08/25 15:14